

PRODUCT DATA SHEET

SikaBond®-58 Wood Floor

LOW VISCOUS WOOD FLOORING ADHESIVE

DESCRIPTION

SikaBond®-58 Wood Floor is a 1-component, solvent-free, wood flooring adhesive with good workability.

USES

SikaBond®-58 Wood Floor is designed for full surface bonding of solid and engineered wood floors and ply boards.

CHARACTERISTICS / ADVANTAGES

- Adhesive can be sanded
- Floors can be sanded after 12 hours
- Elastic, footfall-sound dampening properties
- Suitable for use with underfloor heating
- Very low emissions
- Reduces stress transfer between the wood floor and the substrate
- Good bead stability
- Good workability and plasticity
- Low VOC content

PRODUCT INFORMATION

Chemical Base	Polyurethane
Packaging	2 kg foil pack
Shelf Life	SikaBond®-58 Wood Floor has a shelf life of 9 months from the date of production, if it is stored properly in undamaged, original, sealed packaging, and if the storage conditions are met.
Storage Conditions	SikaBond®-58 Wood Floor shall be stored in dry conditions, protected from direct sunlight and at temperatures between +5 °C and +25 °C.
Colour	Parquet brown
Density	1.30 kg/l approx. (ISO 1183-1)

TECHNICAL INFORMATION

Shore A Hardness	35 approx. (after 28 days)	(ISO 868)
Tensile Strength	1.3 N/mm ² approx.	(ISO 37)
Elongation at Break	360% approx.	(ISO 37)
Shear Strength	1.1 N/mm ² approx., 1 mm adhesive thickness	(ISO 17178)
Service Temperature	+5 °C to +40 °C	

APPLICATION INFORMATION

Consumption	Full Surface Bonding: <ul style="list-style-type: none">▪ 800–1300 g/m² with notched trowel
Sag Flow	SikaBond®-58 Wood Floor spreads very easily whilst maintaining stable trowel marks.
Ambient Air Temperature	+15 °C to +35 °C
Relative Air Humidity	40% to 70%
Substrate Temperature	During laying and until SikaBond®-58 Wood Floor has fully cured, the substrate and ambient temperatures shall be between +15 °C and +35 °C without and between +20 °C and +35 °C with underfloor heating.
Substrate Moisture Content	Permissible substrate moisture content without underfloor heating: <ul style="list-style-type: none">▪ 2.5% CM for cement screeds.▪ 0.5% CM for anhydrite screeds.▪ 3–12% CM for magnetite flooring (depending on the organic content). Permissible substrate moisture content for use with underfloor heating: <ul style="list-style-type: none">▪ 1.8% CM for cement screeds.▪ 0.3% CM for anhydrite screeds.▪ 3–12% CM for magnetite flooring (depending on the organic content). Note: For all moisture contents, the quality of the substrates and surfaces, always follow the guidelines of the wood flooring manufacturer.
Curing Rate	4.5 mm / 24 hours approx. (23 °C / 50% r.h.)
Tack Free Time	60 minutes approx. (23 °C / 50 % r.h.)

BASIS OF PRODUCT DATA

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

FURTHER DOCUMENTS

- Safety Data Sheet
- Pre-treatment Chart Sealing and Bonding
- Method Statement "Full Surface Bonding"

LIMITATIONS

- SikaBond®-58 Wood Floor is only suitable for use by professional wood floor applicators.
- For good workability, the adhesive temperature shall be $\geq +15$ °C.
- For proper curing of the adhesive, sufficient ambient humidity / moisture is necessary.
- A preliminary adhesion test is necessary before any application on glazed tiles.
- Before wood floors may be installed in non-insulated areas, such as basements or other areas without a damp proof membrane, Sikafloor® EpoCem must be applied and sealed with Sika® Primer MB to control the moisture. For detailed instructions, contact our Technical Service Department.
- For use with chemically pre-treated types of wood floors (e.g. those produced or treated with ammonia, wood stain, timber preservative) and woods with a relatively high oil content, SikaBond®-58 Wood Floor is only to be used with the written agreement of our Technical Service Department.

- Do not use on polyethylene (PE), polypropylene (PP), polytetrafluoroethylene (PTFE / Teflon), and other similar plasticized synthetic materials.
- Some other floor priming materials can negatively influence the adhesion of SikaBond®-58 Wood Floor (pre-trials recommended).
- SikaBond®-58 Wood Floor is designed as a wood floor bonding adhesive. When laying parquet type wood floors without tongued and grooved joints, e.g. mosaic parquet floors, avoid the wood floor adhesive extruding into the joints between the wood pieces.
- Avoid contact between any wood surface sealer coatings and adhesive. However, if direct contact with the adhesive is unavoidable, then the compatibility must be checked and confirmed before use of any coatings. For further information and advice, please contact our Technical Service Department.
- Do not expose uncured SikaBond®-58 Wood Floor to alcohol containing products as they may interfere with the curing reaction.
- For further information and advice, please contact our Technical Service Department.

ECOLOGY, HEALTH AND SAFETY

For information and advice on the safe handling, storage and disposal of chemical products, users shall refer to the most recent Safety Data Sheet (SDS) containing physical, ecological, toxicological and other safety-related data.

APPLICATION INSTRUCTIONS

For the application of SikaBond®-58 Wood Floor all standard construction guidelines apply. For further information, please refer to the Method Statement "Full Surface Bonding".

SUBSTRATE PREPARATION

- The substrate must be clean, dry, sound and homogeneous, free from oils, grease, dust and loose or friable particles. Paint, cement laitance and other poorly adhering contaminants must be removed.
- Concrete and/or cement screeds must be ground and thoroughly cleaned with an industrial vacuum.
- Anhydrite screeds, including flowable anhydrite screeds must be ground and thoroughly cleaned with an industrial vacuum shortly before bonding with the adhesive starts.
- Broadcast mastic asphalt must be primed with Sika® Primer MR Fast or Sika® Primer MB. For the instructions for use, please refer to the corresponding Product Data Sheet.
- Glazed ceramic and old existing ceramic tiles must be degreased and cleaned with Sika® Aktivator-205, or the tile surfaces must be ground and then thoroughly cleaned with an industrial vacuum.
- Wood and/or gypsum boards (e.g. chipboard, plywood) must be glued and/or screwed to the substructure in order to be fixed to the substrate. For floating dry-floors, contact our Technical Service Department.
- For other substrates contact our Technical Service Department for advice and assistance.
- For broadcasted mastic asphalt, cement based floors with excessive moisture content and use over old adhesive residues or on weak substrates use Sika® Primer MB. For detailed instructions contact our Technical Service Department.

APPLICATION METHOD / TOOLS

Full Surface Bonding with a Trowel:

- SikaBond®-58 Wood Floor is applied directly from the pail to properly prepared substrates and uniformly spread with a notched trowel.
- SikaBond®-58 Wood Floor can also be applied from foil packs using an application gun
- Press the wood floor pieces firmly into the adhesive so that the wood floor underside is completely covered with the adhesive. The pieces can then be joined together using a hammer and an impact block. Many types of wood floors also have to be tapped into position from above. A distance of 10–15 mm from the wall to the wood floor must be maintained.

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The floor shall be walked on and/or sanded 24 hours after installation (23 °C / 50% r.h. up to 1 mm adhesive thickness depending on the environmental conditions and adhesive layer thickness).

Fresh, uncured adhesive on the wood floor surface must be removed immediately with a clean cloth and if necessary also cleaned with Sika® Remover-208 or Sika® TopClean-T. Always test wood floor surfaces for compatibility with Sika® Cleaner-208 before use. The guidelines of the wood floor manufacturer apply.

CLEANING OF TOOLS

Clean all tools and application equipment immediately after use with Sika® Remover-208 and/or Sika® TopClean T. Once cured, residual material can only be removed mechanically.

LOCAL RESTRICTIONS

Please note that as a result of specific local regulations the performance of this product may vary from country to country. Please consult the local Product Data Sheet for the exact description of the application fields.

LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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